

Bill of Materials

TI DESIGNS
TIDA-00718

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	IPCB	1		TIDA-00718	Any	Printed Circuit Board	
2	C2, C6, C8	3	10uF	CL05A106MP5NUNC	Samsung Electro-	CAP, CERM, 10 μ F, 10 V, +/-	0402
3	C3, C4	2	2.2uF	CL05A225KQ5NNNC	Samsung	CAP, CERM, 2.2 μ F, 6.3 V, +/- 10%, X5R, 0402	0402
4	C5	1	4.7uF	CL05A475MP5NRNC	Samsung Electro-Mechanics	CAP, CERM, 4.7 μ F, 10 V, +/- 20%, X5R, 0402	0402
5	C7, C9, C10	3	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 μ F, 10 V, +/- 10%, X5R, 0402	0402
6	GND	1		6092	Keystone	Standard Banana Jack,	6092
7	J1, J2, J3	3		CONREVSMA002-G	Linx Technologies	SMA Jack, 50Ohm, R/A, TH	SMA Jack
8	J4	1		802-10-006-10-001000	Mill-Max	Header, 2.54 mm, 3x2, Gold,	Header, 2.54 mm, 3x2, TH
9	L1	1	470nH	LQM21PNR47MGH	MuRata	Inductor, Multilayer, Ferrite,	2.0x1.0x1.2mm
10	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
11	TP2, TP3	2	Double	1573-2	Keystone	Terminal, Turret, TH, Double	Keystone1573-2
12	U1	1		LP5907SNX-1.2/NOPB	Texas Instruments	Ultra Low-Noise, 250-mA	DQN0004A
13	U2	1		LM3281YFQR	Texas Instruments	3.3V, 1@A, ^MHz Miniature Step-Down DC_D Converter for WLAN Chipsets, YFQ0006AUAM	YFQ0006AUAM
14	U3	1		LP5907SNX-1.8/NOPB	Texas Instruments	Ultra Low-Noise, 250-mA Linear Regulator for RF and Analog Circuits, DQN0004A	DQN0004A
15	VIN	1		6091	Keystone	Standard Banana Jack, Insulated, Red	6091
16	C1	0	100uF	293D107X0010D2TE3	Vishay-Sprague	CAP, TA, 100 μ F, 10 V, +/- 20%, 0.6 ohm, SMD	7343-31
17	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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